

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD22N08S2L-50	**Issued**	14. May 2021
MA#	MA003176912		
Package	PG-TO252-3-11	**Weight***	370.15 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.714	0.46	0.46	4629	4629
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		582	
	non noble metal	copper	7440-50-8	215.017	58.10	58.18	580890	581646
wire	non noble metal	aluminium	7429-90-5	1.455	0.39	0.39	3931	3931
encapsulation	inorganic material	zincoxide	1314-13-2	1.269	0.34		3429	
	miscellaneous	miscellaneous	-	6.346	1.71		17145	
	plastics	epoxy resin	-	19.038	5.14		51434	
	inorganic material	silicondioxide	60676-86-0	100.268	27.09	34.28	270884	342892
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10104	10104
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.035	0.01		93	
	noble metal	silver	7440-22-4	0.043	0.01		117	
	non noble metal	lead	7439-92-1	1.652	0.45	0.47	4464	4674
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.18	5.19	51810	51878
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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